

Title (en)  
CONDUCTIVE METAL PASTE

Title (de)  
LEITFÄHIGE METALLPASTE

Title (fr)  
PÂTE MÉTALLIQUE CONDUCTRICE

Publication  
**EP 1780732 A1 20070502 (EN)**

Application  
**EP 04746275 A 20040623**

Priority  
JP 2004008806 W 20040623

Abstract (en)  
The present invention provides a conductive metal paste, available for fabrication of a metal fine particle sintered product layer, which has excellent adhesion to a surface of an underlying substrate such as a glass substrate and also has good conductivity. The conductive metal paste according to the present invention contains, per 100 parts by mass of the metal fine particles whose average particle size is 1 to 100 nm, 10 to 60 parts by mass in total of one or more compounds which are used in a coating molecular layer on a surface of a metal fine particle and which have a group capable of coordinate bonding to a metal element contained in the metal fine particles via a lone pair held by a nitrogen, oxygen, or sulfur atom, and also contains one or more metal compounds which are reduced by heating up to 250 °C or higher to be able to precipitate a metal atom such that a total amount of metals contained in the metal compound is within a range from 0.3 to 7 parts by mass, and further, 100 to 500 parts by mass of an amine-based solvent capable of dissolving the metal compounds blended per 10 parts by mass in total of metals in the metal compounds, wherein all of these components are uniformly dissolved and dispersed in an organic solvent used as a dispersion solvent for the metal fine particles.

IPC 8 full level  
**H01B 1/22** (2006.01); **C08K 5/17** (2006.01)

CPC (source: EP US)  
**H01B 1/22** (2013.01 - EP US); **C08K 5/17** (2013.01 - EP US); **C08K 9/04** (2013.01 - EP US); **Y10S 977/773** (2013.01 - EP US); **Y10T 428/29** (2015.01 - EP US)

Cited by  
US8643165B2; WO2016156221A1

Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**EP 1780732 A1 20070502; EP 1780732 A4 20080730; EP 1780732 B1 20090401**; CN 100587855 C 20100203; CN 1973341 A 20070530; DE 602004020396 D1 20090514; JP 4496216 B2 20100707; JP WO2006011180 A1 20080501; US 2008105853 A1 20080508; US 8021580 B2 20110920; WO 2006011180 A1 20060202

DOCDB simple family (application)  
**EP 04746275 A 20040623**; CN 200480043434 A 20040623; DE 602004020396 T 20040623; JP 2004008806 W 20040623; JP 2006526010 A 20040623; US 57124904 A 20040623